

On-Chip Photonics

Guest Editor:

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Deadline for manuscript
submissions:

closed (20 April 2024)

Message from the Guest Editor

The on-chip photonics industry has been growing rapidly thanks to the maturity level that chip foundries have reached in fabricating such chips with industrial-level accuracy and mass production.

In this Special Issue, we invite authors from various fields to present their recent findings in the area of on-chip photonics applications. Areas of interest may include but are not limited to:

1. Co Packaged Optics for telecommunications and optical transceivers;
2. Design of novel photonic devices and systems for telecommunication applications;
3. Novel software and modeling tools for photonic devices and systems;
4. Latest industrial applications and challenges;
5. Applications of metasurfaces in industrial applications;
6. Recent advances in materials for photonic devices;
7. Novel characterization and fabrication methodologies, techniques, and industrial systems;
8. Novel devices and systems for sensing applications;
9. Machine learning and artificial intelligence applications for photonic devices.

We look forward to receiving your submissions and publishing a high-quality Special Issue that showcases the latest advances in on-chip photonics.



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Special Issue